



0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

Product Summary (@TA = +25°C)

V _{RRM} (V)	I _O (A)	V _F (V)	I _R (μA)		
1000	0.8	1.1	5		

Features and Benefits

- Glass Passivated Die Construction
- Miniature Package Saves Space on PC Boards
- Reliable Robust Construction
- Ideal for SMT Manufacturing
- Low Forward Voltage Drop
- Lead-Free Finish; RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)

Description and Applications

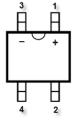
Suitable for AC to DC bridge full wave rectification for SMPS, LED lighting, adapter, battery charger, home appliances, office equipment, and telecommunication applications.

Mechanical Data

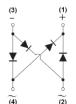
- Case: MBF
- Case Material: Molded Plastic.
 UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Polarity: As Marked on Body
- Weight: 0.08 grams (Approximate)







Pin Diagram



Internal Schematic

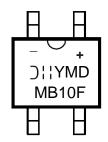
Ordering Information (Note 4)

Part Number	Part Number Compliance		Packaging	
MB10F-13	Commercial	MBF	5,000/Tape & Reel	

Notes:

- 1. EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant. All applicable RoHS exemptions applied.
- 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http://www.diodes.com/products/packages.html.

Marking Information



MB10F= Product Type Marking Code

Oii = Manufacturers' Code Marking

YMD = Date Code Marking

Y = Last Digit of Year (ex: 7 = 2017)

M = See Month/Code Table Below

D = Day 1~9 =1~9; Day 10~31= A~V

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	0	Ν	D

MB10F Document number: DS39046 Rev. 3 - 2



Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

Single phase, half wave, 60Hz, resistive or inductive load.

For capacitive load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	1,000	٧
RMS Reverse Voltage	V _{R(RMS)}	700	V
Average Rectified Output Current (Note 5) @ $T_A = +12$ @ $T_A = +11$		0.5 0.8	Α
Non-Repetitive Peak Forward Surge Current, 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	30	Α
1^2 t Rating for Fusing (1ms < t < 8.3ms)	l ² t	3.74	A ² S

Thermal Characteristics

Characteristic Typical Thermal Resistance, Junction to Ambient (Note 6) (Per Element) Typical Thermal Resistance, Junction to Lead (Per Element) Operating and Storage Temperature Range		Value	Unit
		63	°C/W
		39	°C/W
		-55 to +150	°C

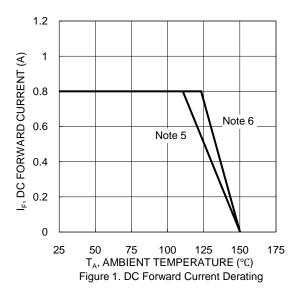
Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

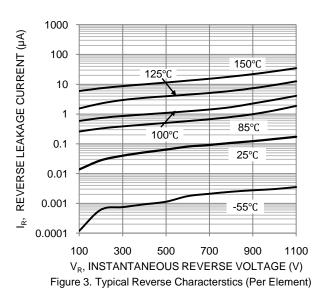
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 7)	$V_{(BR)R}$	1,000	_	_	V	$I_R = 5\mu A$
Forward Voltage (Per Element)	VF	_	0.94	1.1	V	I _F = 0.8A, T _A = +25°C
Leakage Current (Note 7) (Per Element)	I _R	1 1	0.2 14	5 500	μA	V _R = 1,000V, T _A = +25°C V _R = 1,000V, T _A = +125°C
Total Capacitance (Per Element)	C _T		8	_	pF	$V_R = 4V, f = 1.0MHz$

Notes:

- 5. Device mounted on FR-4 substrate, 1"*1", 2oz, single-sided, PC boards with 0.1"*0.15" copper pad.
 6. Device mounted on FR-4 substrate, 1"*1", 2oz, single-sided, PC boards with 0.56"*0.73" copper pad.
 7. Short duration pulse test used to minimize self-heating effect.







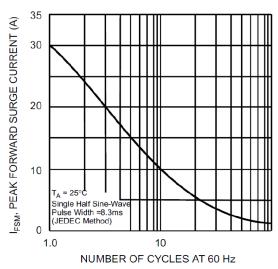


Figure 5. Maximum Peak Forward Surge Current (Per Leg)

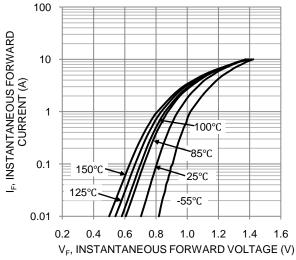
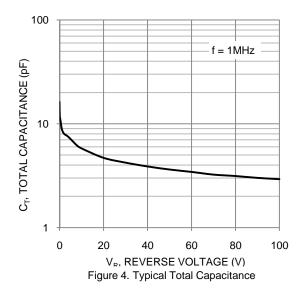


Figure 2. Typical Forward Characterstics (Per Element)



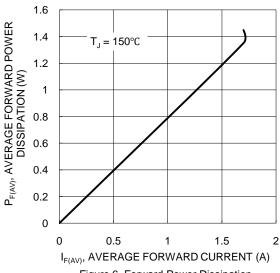


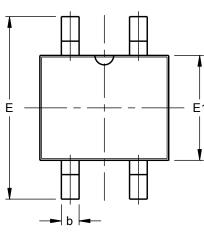
Figure 6. Forward Power Dissipation



Package Outline Dimensions

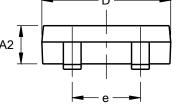
Please see http://www.diodes.com/package-outlines.html for the latest version.

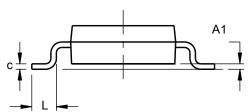
MBF



E1
→ b -
⊢ D →

	MBF							
Dim	Min	Max	Тур					
A1		0.20						
A2	1.20	1.60						
b	0.50	0.80						
С	0.15	0.35						
D	4.50	4.95						
Е	6.40	7.00						
E1	3.60	4.10						
е	2.30	2.70						
Ĺ	0.70	1.10						
All	All Dimensions in mm							

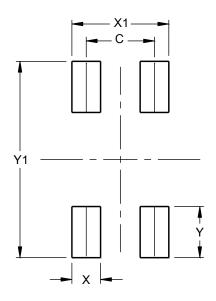




Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

MBF



Dimensions	Value (in mm)		
С	2.50		
Х	1.050		
X1	3.55		
Υ	1.875		
Y1	7 20		



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